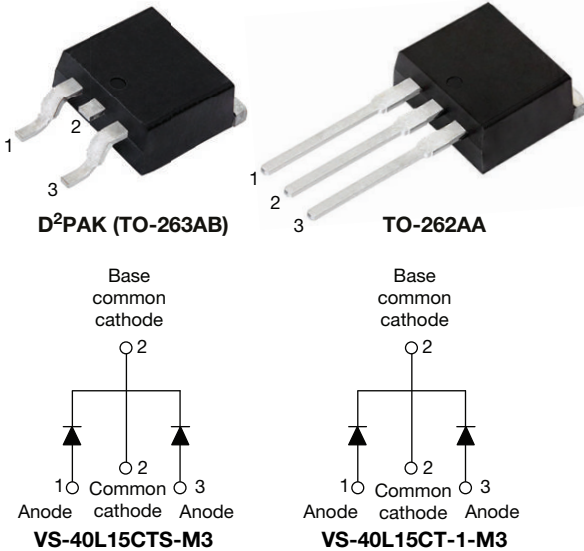


High Performance Schottky Rectifier, 2 x 20 A



FEATURES

- 125 °C T_J operation (V_R < 5 V)
- Center tap module
- Optimized for OR-ing applications
- Ultralow forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

DESCRIPTION

The center tap Schottky rectifier module has been optimized for ultralow forward voltage drop specifically for the OR-ing of parallel power supplies. The proprietary barrier technology allows for reliable operation up to 125 °C junction temperature. Typical applications are in parallel switching power supplies, converters, reverse battery protection, and redundant power subsystems.

PRIMARY CHARACTERISTICS

I _{F(AV)}	2 x 20 A
V _R	15 V
V _F at I _F	0.33 V
I _{RM} max.	600 mA at 100 °C
T _J max.	125 °C
E _{AS}	10 mJ
Package	D ² PAK (TO-263AB), TO-262AA
Circuit configuration	Common cathode

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
I _{F(AV)}	Rectangular waveform	40	A
V _R		15	V
I _{FSM}	t _p = 5 μs sine	700	A
V _F	19 A _{pk} , T _J = 125 °C (per leg, typical)	0.25	V
T _J		-55 to +125	°C

VOLTAGE RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VS-40L15CTS-M3 VS-40L15CT-1-M3	UNITS
Maximum DC reverse voltage	V _R	T _J = 100 °C	15	V
Maximum working peak reverse voltage	V _{RWM}			



ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current, see fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 85\text{ }^\circ\text{C}$, rectangular waveform		20	A
				40	
Maximum peak one cycle non-repetitive surge current per leg, see fig. 7	I_{FSM}	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with rated V_{RRM} applied	700	
		10 ms sine or 6 ms rect. pulse		330	
Non-repetitive avalanche energy per leg	E_{AS}	$T_J = 25\text{ }^\circ\text{C}$, $I_{AS} = 2\text{ A}$, $L = 6\text{ mH}$		10	mJ
Repetitive avalanche current per leg	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical		2	A

ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		TYP.	MAX.	UNITS
Maximum forward voltage drop per leg See fig. 1	$V_{FM}^{(1)}$	19 A	$T_J = 25\text{ }^\circ\text{C}$	-	0.41	V
		40 A		-	0.52	
		19 A	$T_J = 125\text{ }^\circ\text{C}$	0.25	0.33	
		40 A		0.37	0.50	
Reverse leakage current per leg See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_R$	-	10	mA
		$T_J = 100\text{ }^\circ\text{C}$		-	600	
Threshold voltage	$V_{F(TO)}$	$T_J = T_J$ maximum		0.182		V
Forward slope resistance	r_f			7.6		m Ω
Maximum junction capacitance per leg	C_T	$V_R = 5\text{ V}_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^\circ\text{C}$		-	2000	pF
Typical series inductance per leg	L_S	Measured lead to lead 5 mm from package body		8	-	nH
Maximum voltage rate of change	dV/dt	Rated V_R		10 000		V/ μs

Note

(1) Pulse width < 300 μs , duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction temperature range	T_J			-55 to +125	$^\circ\text{C}$
Maximum storage temperature range	T_{Stg}			-55 to +150	
Maximum thermal resistance, junction to case per leg	R_{thJC}	DC operation See fig. 4		1.5	$^\circ\text{C/W}$
Typical thermal resistance, case to heatsink	R_{thCS}	Mounting surface, smooth and greased		0.50	
Maximum thermal resistance, junction to ambient	R_{thJA}	DC operation		40	
Approximate weight				2	g
				0.07	oz.
Mounting torque	minimum	Non-lubricated threads		6 (5)	kgf · cm (lbf · in)
	maximum			12 (10)	
Marking device		Case style D ² PAK (TO-263AB)		40L15CTS	
		Case style TO-262AA		40L15CT-1	

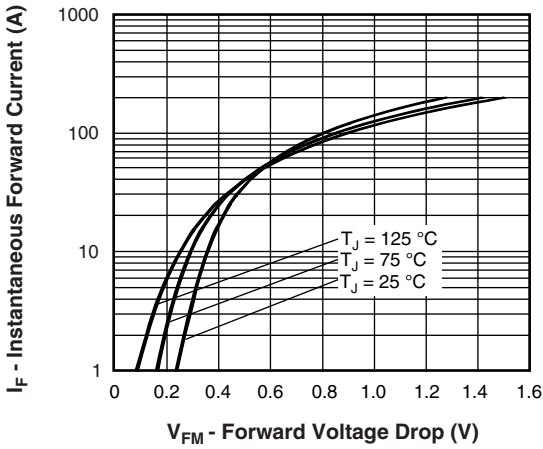


Fig. 1 - Maximum Forward Voltage Drop Characteristics

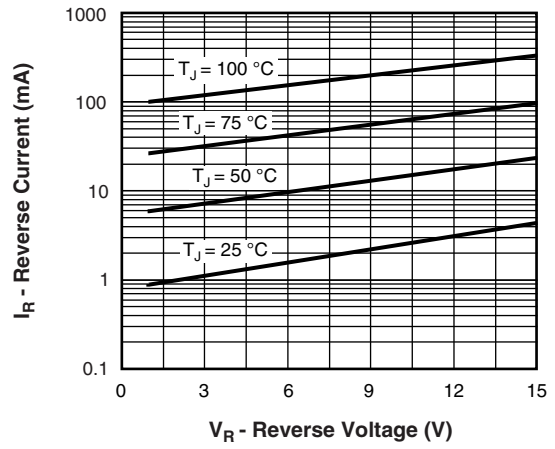


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

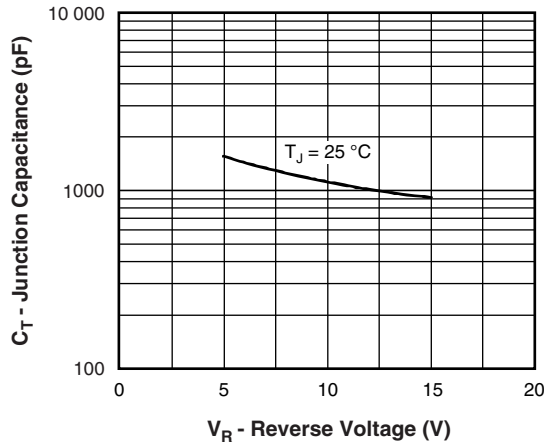


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

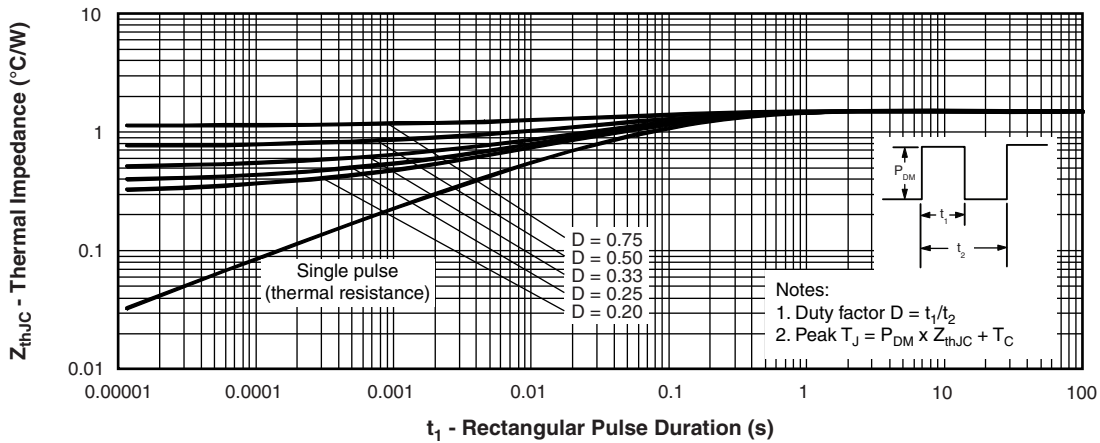


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

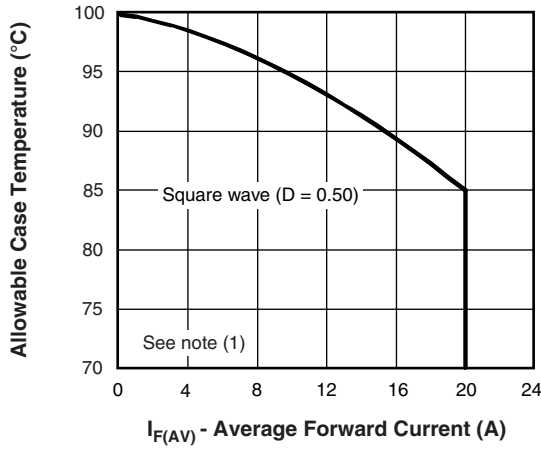


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

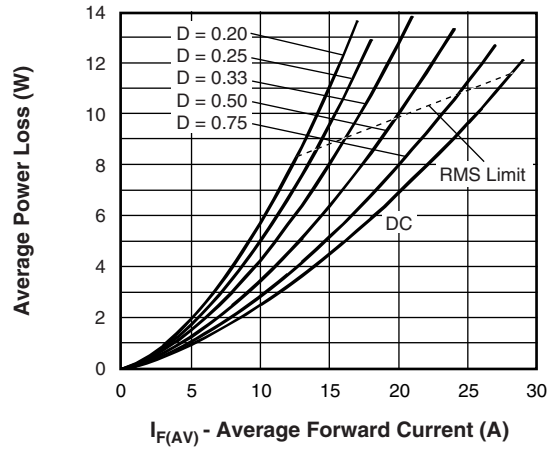


Fig. 6 - Forward Power Loss Characteristics

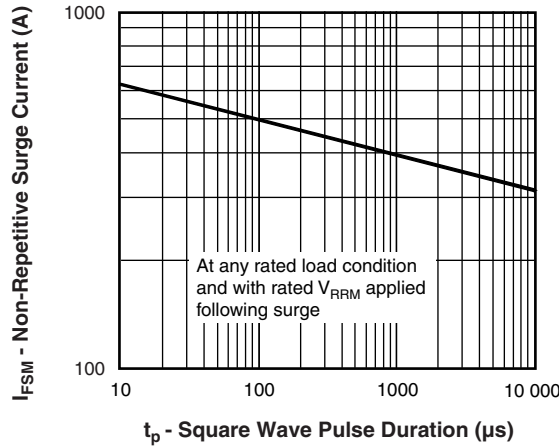


Fig. 7 - Maximum Non-Repetitive Surge Current

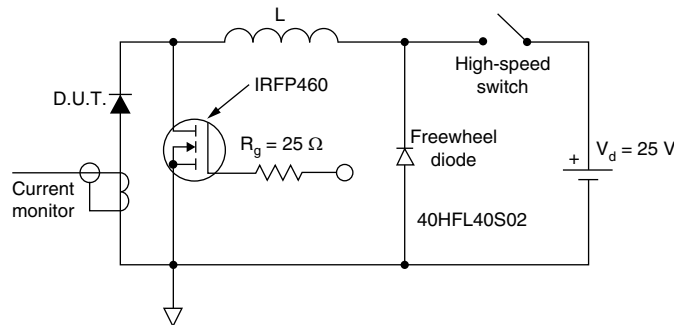


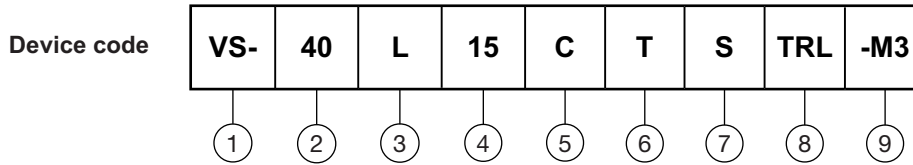
Fig. 8 - Unclamped Inductive Test Circuit

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
- P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
- $P_{d_{REV}}$ = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (40 A)
- 3** - L = Schottky "L" series
- 4** - Voltage rating (15 V)
- 5** - C = common cathode
- 6** - T = TO-220
- 7** -
 - S = D²PAK (TO-263AB)
 - -1 = TO-262AA
- 8** -
 - None = tube
 - TRL = tape and reel (left oriented - for D²PAK (TO-263AB) only)
 - TRR = tape and reel (right oriented - for D²PAK (TO-263AB) only)
- 9** - -M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-40L15CTS-M3	50	Antistatic plastic tubes
VS-40L15CTSTRL-M3	800	13" diameter plastic tape and reel
VS-40L15CTSTRR-M3	800	13" diameter plastic tape and reel
VS-40L15CT-1-M3	50	Antistatic plastic tubes

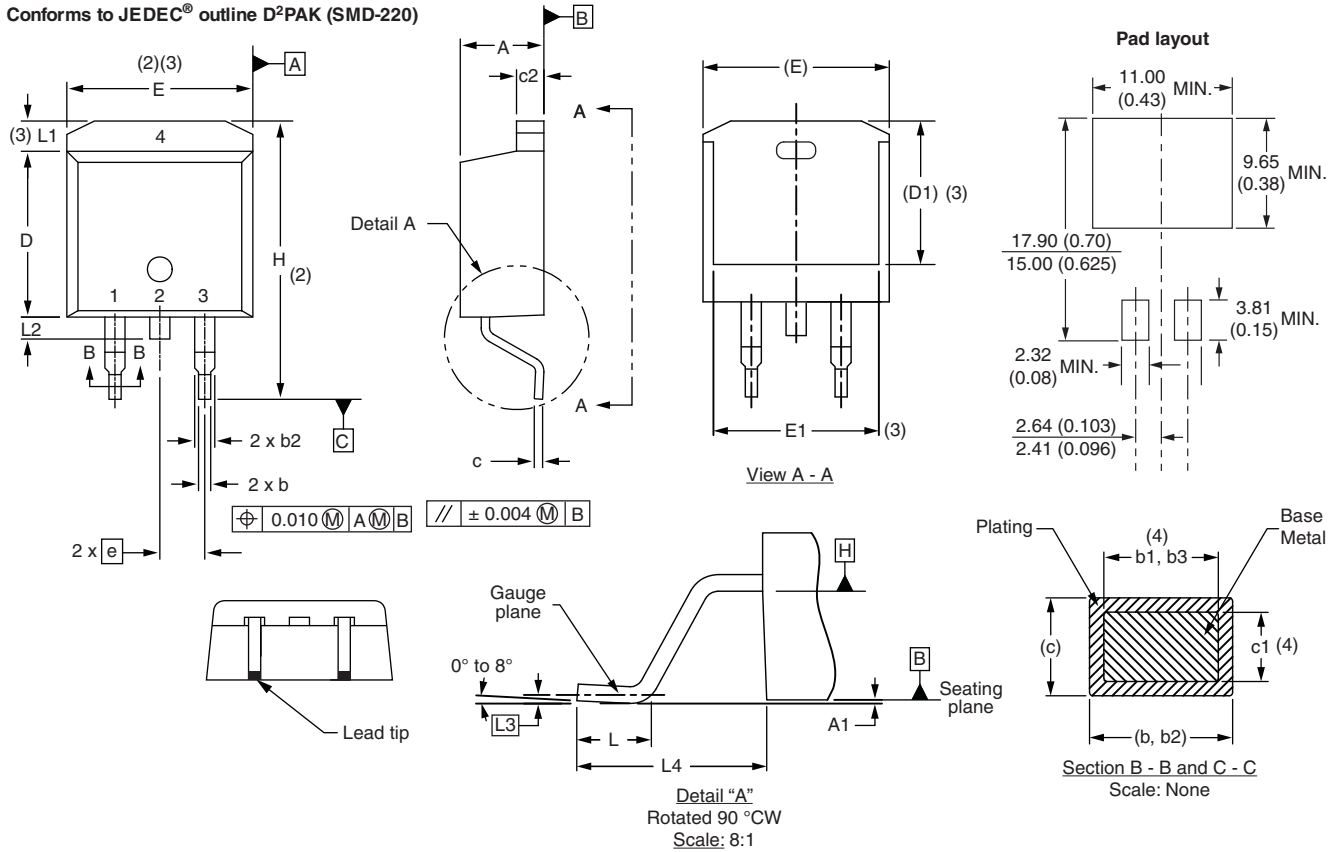
LINKS TO RELATED DOCUMENTS		
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164
	TO-262AA	www.vishay.com/doc?96165
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444
	TO-262AA	www.vishay.com/doc?95443
Packaging information		www.vishay.com/doc?96424



D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010		E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039		E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070		H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4	L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029		L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4	L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065		L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2	L4	4.78	5.28	0.188	0.208	

Notes

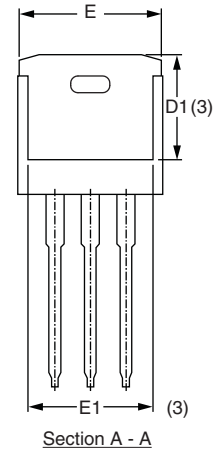
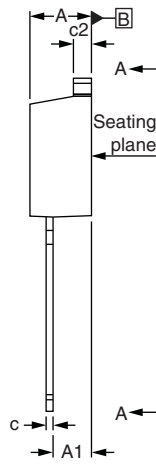
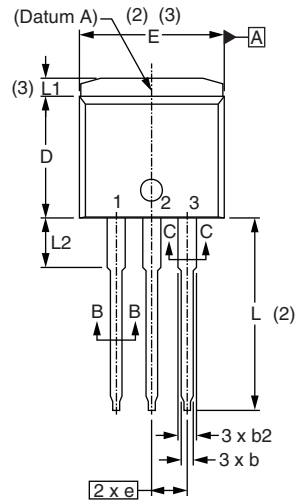
- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



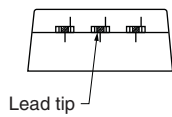
TO-262

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262

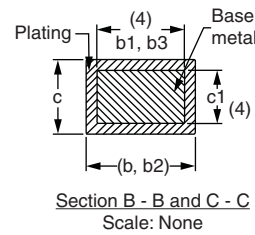


$\phi 0.010 \text{ M} \text{ A} \text{ M} \text{ B}$



Lead assignments

- Diodes
 1. - Anode (two die)/open (one die)
 2., 4. - Cathode
 3. - Anode



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
 (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
 (3) Thermal pad contour optional within dimension E, L1, D1 and E1
 (4) Dimension b1 and c1 apply to base metal only
 (5) Controlling dimension: inches
 (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



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